'8-15-05; 5:14PM; 17038729306 ;19496600809 # 3/ 13

Application No.: 10/603,924

Docket No.: JCLA7109

## In The Title:

POST CMP REMOVAL OF SURFACE CONTAMINANTS FROM SILICON

WAFER METHOD OF REMOVING CONTAMINANTS FROM A SILICON WAFER AFTER

CHEMICAL-MECHANICAL POLISHING OPERATION